T428 Series High Volumetric Efficiency Facedown Commercial Off-The-Shelf (COTS) MnO₂



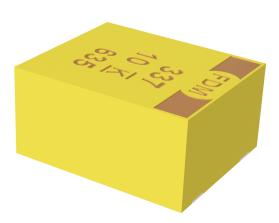
Overview

The KEMET T428 Series was developed to provide the volumetric efficiency of a conformally coated capacitor in a pick-and-place friendly molded package. The planerity of the molded package eliminates the "drops" associated with the conformally coated tantalum surface mount devices. This new package design offers the highest CV/cc of

any molded leadframe product. In addition, the facedown construction offers higher power ratings per cc. The robust design features and testing protocol make this part suitable for application in the telecommunications, industrial, military and aerospace markets.

Benefits

- High CV/cc
- Taped and reeled per EIA 481
- · SnPb termination finish
- · Laser-marked case
- 100% surge current test available
- Halogen-free epoxy
- Capacitance values of 15 to 470 μF
- Tolerances of ±5%, ±10%, and ±20%
- Voltage rating of 4 to 50 VDC
- Extended range values
- Pick-and-place friendly
- · RoHS Compliant and lead-free terminations available
- Operating temperature range of -55°C to +125°C



Applications

Typical applications include decoupling and filtering in telecommunications, computer, industrial, defense and aerospace applications.

Environmental Compliance

RoHS Compliant (6/6) according to Directive 2002/95/EC when ordered with 100% Sn solder.

K-SIM

For a detailed analysis of specific part numbers, please visit ksim.kemet.com to access KEMET's K-SIM software. KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels.



Ordering Information

Т	428	Р	337	K	010	Α	Н	61	10
Capacitor Class	Series	Case Size	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VDC)	Failure Rate/ Design	Termination Finish	Surge	ESR
T = Tantalum	High Volumetric Efficiency Facedown Hi-Rel MnO ₂ COTS	Р	First two digits represent significant figures. Third digit specifies number of zeros.	J = ±5% K = ±10% M = ±20%	004 = 4 006 = 6.3 010 = 10 016 = 16 020 = 20 025 = 25 035 = 35 050 = 50	A = N/A B = 0.1%/ 1,000 hours	H = Standard solder coated (SnPb 5% Pb)	61 = None 62 = 10 cycles, 25°C 63 = 10 cycles, -55°C and 85°C	10 = Standard 20 = Low 30 = Ultra-low

Performance Characteristics

Item	Performance Characteristics			
Operating Temperature	-55°C to 125°C			
Rated Capacitance Range	15 - 470 μF at 120 Hz/25°C			
Capacitance Tolerance	J Tolerance (5%), K Tolerance (10%), M Tolerance (20%)			
Rated Voltage Range	4 – 50 V			
DF (120 Hz)	Refer to Part Number Electrical Specification Table			
ESR (100 kHz)	Refer to Part Number Electrical Specification Table			
Leakage Current	≤ 0.01 CV (µA) at rated voltage after 5 minutes			



Qualification

Test	Condition		Characteristics				
		Δ C/C	Within ±10%	6 of initial valu	е		
Endurance	85°C at rated voltage, 2,000 hours	DF	Within initial limits				
	125°C at 2/3 rated voltage, 2,000 hours		DCL	Within 1.25	Within 1.25 x initial limit		
		ESR	Within initia	al limits			
			Δ C/C	Within ±109	6 of initial valu	e	
04	105°0 -4 0 la- 0 000 h		DF	Within initia	al limits		
Storage Life	125°C at 0 volts, 2,000 hours		DCL	Within 1.25	x initial limit		
		ESR	Within initial limits				
			Δ C/C	Within ±5%	of initial value		
TI 101 1	MIL-STD-202, Method 107, Condition B, mo	DF	Within initial limits				
Thermal Shock	-55°C to 125°C, 1,000 cycles	DCL	Within 1.25	x initial limit			
		ESR	Within initia	Within initial limits			
		+25°C	-55°C	+85°C	+125°C		
T . 0. 1.11.	Extreme temperature exposure at a	Δ C/C	IL*	±10%	±10%	±20%	
Temperature Stability	succession of continuous steps at +25°C, -55°C, +25°C, +85°C, +125°C, +25°C	DF	IL	IL	1.5 x IL	1.5 x IL	
		DCL	IL	n/a	10 x IL	12 x IL	
			Δ C/C	Within ±5% of initial value			
	85°C, 1.32 x rated voltage 1,000 cycles	85°C 1.32 x rated voltage 1.000 cycles					
Surge Voltage	(125°C, 1.2 x rated voltage)	DCL	Within initial limits				
		ESR	Within initial limits				
	MIL-STD-202, Method 213, Condition I, 100	G neak	Δ C/C	Within ±10 of initial value			
Mechanical Shock/ Vibration	MIL-STD-202, Method 204, Condition D, 10	DF	Within initial limits				
VIDIATION	2,000 Hz, 20 G peak	DCL	Within initial limits				
Additional Qualification Tests per MIL-PRF- 55365/8	Please contact KEMET for more information.						

^{*}IL = Initial limit

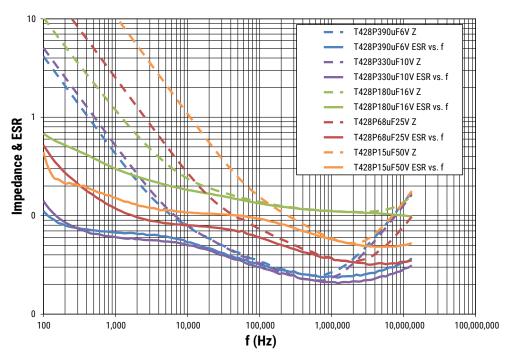
Certification

MIL-PRF-55365/8

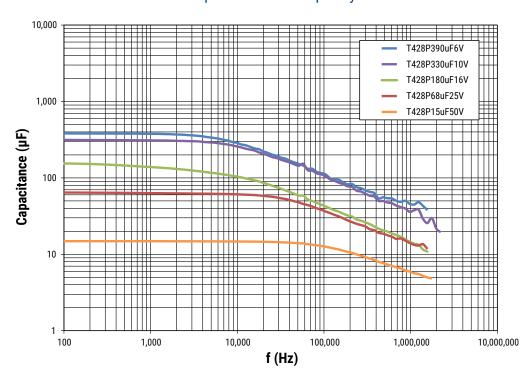


Electrical Characteristics

Impedance & ESR vs. Frequency

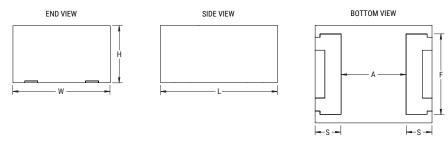


Capacitance vs. Frequency





Dimensions - Millimeters



Case Size		Component								
EIA	L Max	W ±0.3	H ±0.3	F ±0.20	S ±0.20	A (Nom)	(mg)			
7360-38	7.2	6.0	3.5	4.95	1.6	3.8	0.86			

These weights are provided as reference. If exact weights are needed, please contact your KEMET Sales Representative

Table 1 - Ratings & Part Number Reference

Rated Voltage	Rated Cap	Case Code/ Case Size	Code/ Number Leakage DF Standard ESR ESR		Low ESR	Ultra- Low ESR	Maximum Operating Temp	MSL		
VDC @ 85°C	μF	KEMET/EIA	(See below for part options)	µA @ +20°C Maximum/ 5 Minutes	%@ +20°C 120 Hz Maximum	mΩ @ +20°C 100 kHz Maximum	mΩ @ +20°C 100 kHz Maximum	Ω @ +20°C 100 kHz Maximum	°C	Reflow Temp ≤ 260°C
4	470	P/7360-38	T428P477(1)004(2)(3)(4)(5)	18.8	10.0	130	45	NA	125	1
6.3	390	P/7360-38	T428P397(1)006(2)(3)(4)(5)	24.6	8.0	130	45	NA	125	1
6.3	470	P/7360-38	T428P477(1)006(2)(3)(4)(5)	29.6	10.0	120	50	NA	125	1
10	330	P/7360-38	T428P337(1)010(2)(3)(4)(5)	33.0	8.0	130	45	NA	125	1
16	180	P/7360-38	T428P187(1)016(2)(3)(4)(5)	28.8	8.0	130	55	NA	125	1
16	220	P/7360-38	T428P227(1)016(2)(3)(4)(5)	35.2	8.0	120	55	NA	125	1
20	150	P/7360-38	T428P157(1)020(2)(3)(4)(5)	30.0	8.0	140	100	NA	125	1
25	68	P/7360-38	T428P686(1)025(2)(3)(4)(5)	17.0	6.0	200	95	NA	125	1
35	22	P/7360-38	T428P226(1)035(2)(3)(4)(5)	7.7	6.0	280	220	NA	125	1
50	15	P/7360-38	T428P156(1)050(2)(3)(4)(5)	7.5	6.0	400	350	NA	125	1

⁽¹⁾ To complete KEMET part number, insert M for ±20%, K for ±10% or J for ±5%. Designates capacitance tolerance.

Please refer to Ordering Information for additional details.

⁽²⁾ To complete KEMET part number, insert B (0.1%/1,000 hours) or A = N/A.

⁽³⁾ To complete KEMET part number, insert H = solder plated. Designates termination finish.

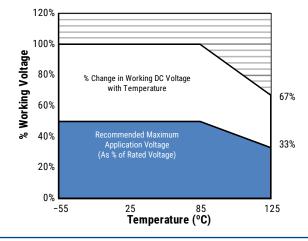
⁽⁴⁾ To complete KEMET part number, insert 61 = none, 62 = 10 cycles $+25^{\circ}$ C, 63 = 10 cycles -55° C $+85^{\circ}$ C after Weibull or 64 = 10 cycles -55° C $+85^{\circ}$ C before Weibull. Designates surge current option.

⁽⁵⁾ To complete KEMET part number, insert 10 = standard, 20 = ILow or 30 = ultra-low. Designates ESR option.



Recommended Voltage Derating Guidelines

	-55°C to 85°C	85°C to 125°C
% Change in Working DC Voltage with Temperature	V_R	67% of V _R
Recommended Maximum Application Voltage	50% of V _R	33% of V _R



Ripple Current/Ripple Voltage

Permissible AC ripple voltage and current are related to equivalent series resistance (ESR) and the power dissipation capabilities of the device. Permissible AC ripple voltage which may be applied is limited by two criteria:

- 1. The positive peak AC voltage plus the DC bias voltage, if any, must not exceed the DC voltage rating of the capacitor.
- 2. The negative peak AC voltage in combination with bias voltage, if any, must not exceed the allowable limits specified for reverse voltage. See the Reverse Voltage section for allowable limits.

The maximum power dissipation by case size can be determined using the table at right. The maximum power dissipation rating stated in the table must be reduced with increasing environmental operating temperatures. Refer to the table below for temperature compensation requirements.

Temperature Compensation Multipliers for Maximum Ripple Current						
T ≤ 25°C	T ≤ 85°C	T ≤ 125°C				
1.00	0.90	0.40				

T= Environmental Temperature

The maximum power dissipation rating must be reduced with increasing environmental operating temperatures. Refer to the Temperature Compensation Multiplier table for details

KEMET Case Code	EIA Case Code	Maximum Power Dissipation (P max) mWatts @ 25°C w/+20°C Rise
Р	7360-38	325

Using the P max of the device, the maximum allowable rms ripple current or voltage may be determined.

 $I(max) = \sqrt{P max/R}$ $E(max) = Z \sqrt{P max/R}$

I = rms ripple current (amperes)

E = rms ripple voltage (volts)

P max = maximum power dissipation (watts)

R = ESR at specified frequency (ohms)

Z = Impedance at specified frequency (ohms)



Reverse Voltage

Solid tantalum capacitors are polar devices and may be permanently damaged or destroyed if connected with the wrong polarity. The positive terminal is identified on the capacitor body by a stripe, plus in some cases a beveled edge. A small degree of transient reverse voltage is permissible for short periods per the below table. The capacitors should not be operated continuously in reverse mode, even within these limits.

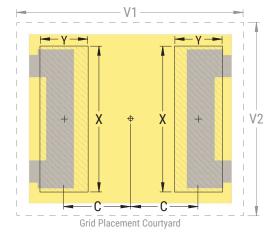
Temperature	Permissible Transient Reverse Voltage
25°C	15% of Rated Voltage
85°C	5% of Rated Voltage
125°C	1% of Rated Voltage

Table 2 - Land Dimensions/Courtyard

KEMET	Metric Size Code	Density Level A: Maximum (Most) Land Protrusion (mm)			ı	Density Level B: Median (Nominal) Land Protrusion (mm)				Density Level C: Minimum (Least) Land Protrusion (mm)						
Case	EIA	X	Y	C	V 1	V2	Х	Y	C	V1	V2	X	Y	С	V1	V2
Р	7360-38	5.25	1.80	2.35	8.50	7.30	5.15	1.70	2.35	8.00	6.80	5.05	1.60	2.35	7.70	6.50

Density Level A: For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes.

Density Level B: For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes. **Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC Standard 7351 (IPC-7351).





Soldering Process

KEMET's families of surface mount capacitors are compatible with wave (single or dual), convection, IR, or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020D standard for moisture sensitivity testing. The devices can safely withstand a maximum of three reflow passes at these conditions.

Please note that although the X/7343-43 case size can withstand wave soldering, the tall profile (4.3 mm maximum) dictates care in wave process development.

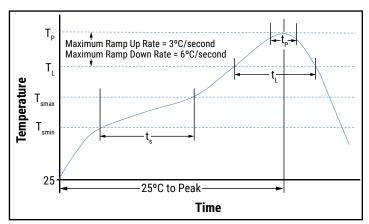
Hand soldering should be performed with care due to the difficulty in process control. If performed, care should be taken to avoid contact of the soldering iron to the molded case. The iron should be used to heat the solder pad, applying solder between the pad and the termination, until reflow occurs. Once reflow occurs, the iron should be removed immediately. "Wiping" the edges of a chip and heating the top surface is not recommended.

During typical reflow operations, a slight darkening of the gold-colored epoxy may be observed. This slight darkening is normal and not harmful to the product. Marking permanency is not affected by this change.

Profile Feature	SnPb Assembly	Pb-Free Assembly
Preheat/Soak		
Temperature Minimum (T _{Smin})	100°C	150°C
Temperature Maximum (T _{Smax})	150°C	200°C
Time (t_s) from T_{smin} to T_{smax})	60 - 120 seconds	60 - 120 seconds
Ramp-up Rate (T _L to T _P)	3°C/seconds maximum	3°C/seconds maximum
Liquidous Temperature (T _L)	183°C	217°C
Time Above Liquidous (t _L)	60 - 150 seconds	60 – 150 seconds
Peak Temperature (T _P)	220°C* 235°C**	250°C* 260°C**
Time within 5°C of Maximum Peak Temperature (t _P)	20 seconds maximum	30 seconds maximum
Ramp-down Rate $(T_P \text{ to } T_L)$	6°C/seconds maximum	6°C/seconds maximum
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum

Note: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow.

^{**}Case Size A, B, C, H, I, K, M, R, S, T, U, V, W, and Z



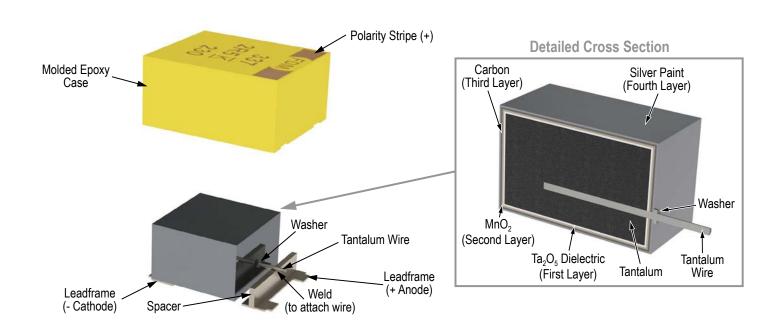
Storage

Tantalum chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature – reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 60% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulphur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within three years of receipt.

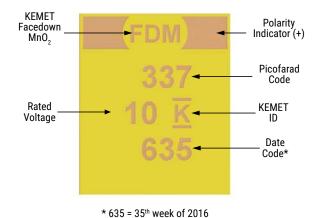
^{*}Case Size D, E, P, Y, and X



Construction



Capacitor Marking



Date (Joue "
1st digit = Last number of Year	2 = 2012
-	3 = 2013
	4 = 2014
	5 = 2015
	6 = 2016
	7 = 2017
2 nd and 3 rd digit = Week of the Year	01 = 1 st week of the Year to 52 = 52 nd week of the Year



Tape & Reel Packaging Information

KEMET's molded chip capacitor families are packaged in 8 and 12 mm plastic tape on 7" and 13" reels in accordance with *EIA Standard 481*: Embossed Carrier Taping of Surface Mount Components for Automatic Handling. This packaging system is compatible with all tape-fed automatic pick-and-place systems.

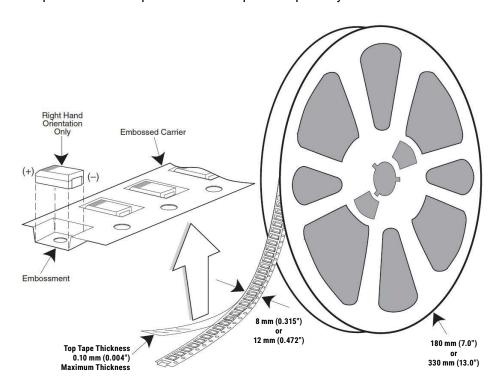


Table 3 - Packaging Quantity

Case Code		Tape Width (mm)	7" Reel*	13" Reel*	
KEMET	EIA				
S	3216-12	8	2,500	10,000	
T	3528-12	8	2,500	10,000	
М	3528-15	8	2,000	8,000	
U	6032-15	12	1,000	5,000	
L	6032-19	12	1,000	3,000	
W	7343-15	12	1,000	3,000	
Z	7343-17	12	1,000	3,000	
V	7343-20	12	1,000	3,000	
Α	3216-18	8	2,000	9,000	
В	3528-21	8	2,000	8,000	
С	6032-28	12	500	3,000	
D	7343-31	12	500	2,500	
Q	7343-12	12	1,000	3,000	
Υ	7343-40	12	500	2,000	
Х	7343-43	12	500	2,000	
E/T428P	7360-38	12	500	2,000	
Н	7360-20	12	1,000	2,500	

^{*} No C-Spec required for 7" reel packaging. C-7280 required for 13" reel packaging.



Figure 1 – Embossed (Plastic) Carrier Tape Dimensions

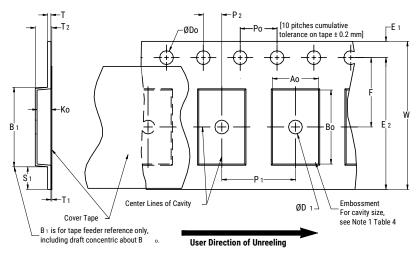


Table 4 - Embossed (Plastic) Carrier Tape Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)									
Tape Size	D ₀	D ₁ Minimum Note 1	E ₁	P ₀	P ₂	R Reference Note 2	S ₁ Minimum Note 3	Mayımıım	T ₁ Maximum
8 mm		1.0 (0.039)			2.0±0.05	25.0 (0.984)			
12 mm	1.5+0.10/-0.0 (0.059+0.004/-0.0)	1.5	1.75±0.10 (0.069±0.004)	4.0±0.10 (0.157±0.004)	(0.079±0.002)	30	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
16 mm	(0.003 + 0.00 1, 0.0)	(0.059)	(33333 2000 1)	(0.107_0.100.1)	2.0±0.1 (0.079±0.059)	(1.181)	(0.02.)	(=====)	(3130.1)

Variable Dimensions — Millimeters (Inches)								
Tape Size	Pitch	B ₁ Maximum Note 4	E ₂ Minimum	F	P ₁	T ₂ Maximum	W Maximum	A ₀ , B ₀ & K ₀
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5±0.05 (0.138±0.002)	2.0±0.05 or 4.0±0.10 (0.079±0.002 or 0.157±0.004)	2.5 (0.098)	8.3 (0.327)	
12 mm	Single (4 mm) & Double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5±0.05 (0.217±0.002)	2.0±0.05 (0.079±0.002) or 4.0±0.10 (0.157±0.004) or 8.0±0.10 (0.315±0.004)	4.6 (0.181)	12.3 (0.484)	Note 5
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	7.5±0.10 (0.295±0.004)	4.0±0.10 (0.157±0.004) to 12.0±0.10 (0.472±0.004)	8.0 (0.315)	16.3 (0.642)	

- 1. The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.
- 2. The tape, with or without components, shall pass around R without damage (see Figure 4).
- 3. If S, < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481–D, paragraph 4.3, section b).
- 4. B_1 dimension is a reference dimension for tape feeder clearance only.
- 5. The cavity defined by A_{or} B_{or} and K_{or} shall surround the component with sufficient clearance that:
 - (a) the component does not protrude above the top surface of the carrier tape.
 - (b) the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
 - (c) rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 2).
 - (d) lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 3).
 - (e) see Addendum in EIA Standard 481–D for standards relating to more precise taping requirements.



Packaging Information Performance Notes

1. Cover Tape Break Force: 1.0 Kg minimum.

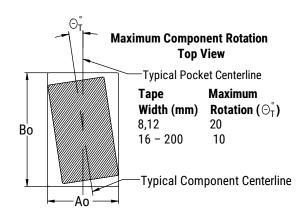
2. Cover Tape Peel Strength: The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength		
8 mm	0.1 to 1.0 Newton (10 to 100 gf)		
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)		

The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 ±10 mm/minute.

3. Labeling: Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. *Refer to EIA Standards 556 and 624*.

Figure 2 - Maximum Component Rotation



Maximum Component Rotation Side View \bigcirc_s° Tape Maximum Width (mm) Rotation (\bigcirc_s°) 8,12 20 16 - 56 10 72 - 200 5

Figure 3 – Maximum Lateral Movement

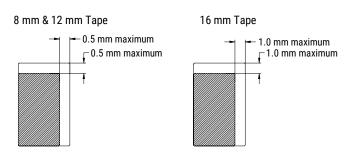


Figure 4 - Bending Radius

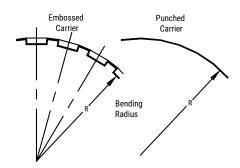
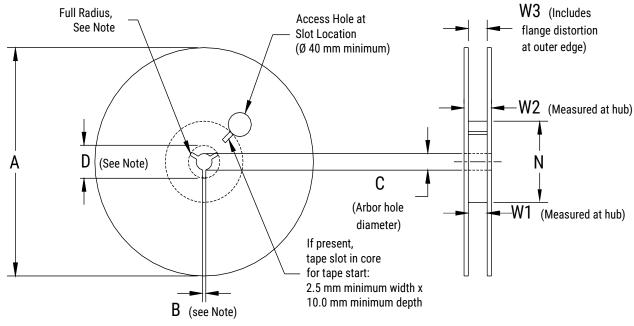




Figure 5 - Reel Dimensions



Note: Drive spokes optional; if used, dimensions B and D shall apply.

Table 5 - Reel Dimensions

Metric will govern

Constant Dimensions — Millimeters (Inches)								
Tape Size	A	B Minimum	С	D Minimum				
8 mm	178±0.20							
12 mm	(7.008±0.008) or	1.5 (0.059)	13.0+0.5/-0.2 (0.521+0.02/-0.008)	20.2 (0.795)				
16 mm	330±0.20 (13.000±0.008)			(0.793)				
	Variable Dimensions — Millimeters (Inches)							
Tape Size	N Minimum	W ₁	W ₂ Maximum	W ₃				
8 mm		8.4+1.5/-0.0 (0.331+0.059/-0.0)	14.4 (0.567)					
12 mm	50 (1.969)	12.4+2.0/-0.0 (0.488+0.078/-0.0)	18.4 (0.724)	Shall accommodate tape width without interference				
16 mm		16.4+2.0/-0.0 (0.646+0.078/-0.0)	22.4 (0.882)					



Figure 6 - Tape Leader & Trailer Dimensions

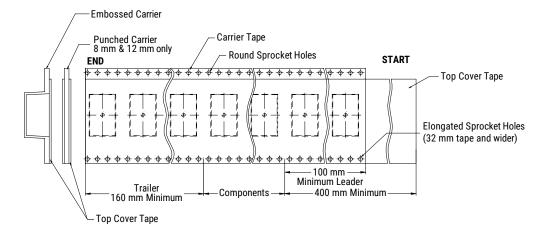
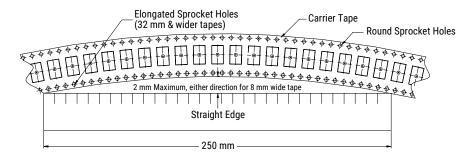


Figure 7 – Maximum Camber





KEMET Electronics Corporation Sales Offices

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Although KEMET designs and manufactures its products to the most stringent quality and safety standards, given the current state of the art, isolated component failures may still occur. Accordingly, customer applications which require a high degree of reliability or safety should employ suitable designs or other safeguards (such as installation of protective circuitry or redundancies) in order to ensure that the failure of an electrical component does not result in a risk of personal injury or property damage.

Although all product-related warnings, cautions and notes must be observed, the customer should not assume that all safety measures are indicted or that other measures may not be required.